Product Change Notification - KSRA-20OSOQ751

Date: 31 Aug 2017

Product Category: Memory; Power Management - PWM Controllers; Sigma - Delta A/D Converters; Digital Potentiometers; System D/A Converters; Instrumentation Amplifier; Battery Management and Fuel Gauges - Battery Chargers; Temperature Sensors; 8-bit PIC Microcontrollers

Notification subject: CCB 3041 and CCB 3073 Initial Notice: Qualification of CuPdAu bond in selected products of the 160K wafer technology available in 8L DFN package at NSEB assembly site

Notification text:

PCN Status:
Initial notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 160K wafer technology available in 8L DFN package at NSEB assembly site

Pre Change:
Using gold (Au) bond wire, 8200T or 8600 die attach material, G770HCD or G700LTD molding compound material and C194 or EFTEC-64T lead frame material

Post Change:
Using palladium coated copper with gold flash (CuPdAu) bond wire 8600 die attach material, G700LTD molding compound material and C194 lead frame material

Pre and Post Change Summary:

	Pre Change			Post Change
Assembly Site	NSEB Assembly Site			NSEB Assembly Site
Wire material	Au Wire			CuPdAu Wire
Die attach material	8200T	8600	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD	G700LTD
Lead frame material	C194	C194	EFTEC-64T	C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:
January 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2017					-->	January 2018				
Workweek	31	32	33	34	35		01	02	03	04	05
Initial PCN Issue Date	X										
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:
August 05, 2017: Issued initial notification.
August 31, 2017: Re-issued initial notification to include CCB 3073.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-20OSOQ751_Affected CPN.pdf
PCN_KSRA-20OSOQ751_Qual Plan.pdf
PCN_KSRA-20OSOQ751_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

KSRA-20OSOQ751 -CCB 3041 and 3073 Initial Notice: Qualification of CuPdAu bond in selected products of the 160K wafer technology available in 8L DFN package at NSEB assembly site

Affected Catalog Part Numbers (CPN)

PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
11LC161T-E/MC
24AA014-I/MC
24AA014T-I/MC
24AA01T-I/MC
24AA024-I/MC
24AA024T-I/MC
24AA025-I/MC
24AA025T-I/MC
24AA02T-I/MC
24AA04-I/MC
24AA04T-I/MC
24AA08-I/MC
24AA08T-I/MC
24AA128-I/MF
24AA128T-I/MF
24AA16-I/MC
24AA16T-I/MC
24AA256-E/MF
24AA256-I/MF
24AA256T-E/MF
24AA256T-I/MF
24AA32AT-I/MC
24AA512-I/MF
24AA512T-I/MF
24AA52-I/MC
24AA52T-I/MC
24AA64T-I/MC
24C01C-E/MC
24C01C-I/MC
24C01CT-E/MC
24C01CT-I/MC
24C02C-E/MC
24C02CT-E/MC
24C02CT-I/MC
24FC128-I/MF
24FC128T-I/MF
24FC256-I/MF
24FC256T-I/MF
24FC512-I/MF
24FC512T-I/MF
24FC64-I/MC
24FC64T-I/MC
24LC014-E/MC

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PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
24LC014-I/MC
24LC014T-E/MC
24LC014T-I/MC
24LC01B-E/MC
24LC01BT-E/MC
24LC01BT-I/MC
24LC024-E/MC
24LC024-I/MC
24LC024T-E/MC
24LC024T-I/MC
24LC025-E/MC
24LC025-I/MC
24LC025T-E/MC
24LC025T-I/MC
24LC02BT-E/MC
24LC02BT-I/MC
24LC04B-E/MC
24LC04B-I/MC
24LC04BT-E/MC
24LC04BT-I/MC
24LC08B-E/MC
24LC08B-I/MC
24LC08BT-E/MC
24LC08BT-I/MC
24LC128-E/MF
24LC128-I/MF
24LC128T-E/MF
24LC128T-I/MF
24LC16B-E/MC
24LC16B-I/MC
24LC16BT-E/MC
24LC16BT-I/MC
24LC256-E/MF
24LC256-I/MF
24LC256T-E/MF
24LC256T-I/MF
24LC32AT-E/MC
24LC32AT-I/MC
24LC32AT-I/MCA28
24LC512-E/MF
24LC512-I/MF
24LC512T-E/MF
24LC512T-I/MF

KSRA-20OSOQ751 -CCB 3041 and 3073 Initial Notice: Qualification of CuPdAu bond in selected products of the 160K wafer technology available in 8L DFN package at NSEB assembly site

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PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
24LC64T-E/MC
24LC64T-I/MC
24LCS52-I/MC
24LCS52T-I/MC
25AA010AT-I/MC
25AA020AT-I/MC
25AA040AT-I/MC
25AA1024-I/MF
25AA1024T-I/MF
25AA128-I/MF
25AA128T-I/MF
25AA256-E/MF
25AA256-I/MF
25AA256T-E/MF
25AA256T-I/MF
25AA512-I/MF
25AA512T-I/MF
25AA640A-E/MF
25AA640A-I/MF
25AA640A-I/MFB22
25AA640AT-E/MF
25AA640AT-I/MFB22
25LC010AT-E/MC
25LC010AT-I/MC
25LC020AT-E/MC
25LC020AT-I/MC
25LC040AT-E/MC
25LC040AT-I/MC
25LC1024-E/MF
25LC1024-I/MF
25LC1024T-E/MF
25LC1024T-I/MF
25LC128-E/MF
25LC128-I/MF
25LC128T-E/MF
25LC128T-I/MF
25LC256-E/MF
25LC256-I/MF
25LC256-I/MF16K
25LC256-M/MF
25LC256T-E/MF
25LC256T-I/MF
25LC256T-I/MF16K

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PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
25LC256T-M/MF
25LC512-E/MF
25LC512-I/MF
25LC512T-E/MF
25LC512T-I/MF
25LC640A-E/MF
25LC640A-I/MF
MCP1632-AAE/MC
MCP1632-BAE/MC
MCP1632T-AAE/MC
MCP1632T-BAE/MC
MCP3422A0-E/MC
MCP3422A0T-E/MC
MCP3422A1-E/MC
MCP3422A1T-E/MC
MCP3422A2-E/MC
MCP3422A2T-E/MC
MCP3422A3-E/MC
MCP3422A3T-E/MC
MCP3422A4-E/MC
MCP3422A4T-E/MC
MCP3422A5-E/MC
MCP3422A5T-E/MC
MCP3422A6-E/MC
MCP3422A6T-E/MC
MCP3422A7-E/MC
MCP3422A7T-E/MC
MCP3426A0-E/MC
MCP3426A0T-E/MC
MCP3426A1-E/MC
MCP3426A1T-E/MC
MCP3426A2-E/MC
MCP3426A2T-E/MC
MCP3426A3-E/MC
MCP3426A3T-E/MC
MCP3426A4-E/MC
MCP3426A4T-E/MC
MCP3426A5-E/MC
MCP3426A5T-E/MC
MCP3426A6-E/MC
MCP3426A6T-E/MC
MCP3426A7-E/MC
MCP3426A7T-E/MC

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
MCP4011T-103E/MC
MCP4011T-202E/MC
MCP4011T-502E/MC
MCP4011T-503E/MC
MCP4021T-103E/MC
MCP4021T-202E/MC
MCP4021T-502E/MC
MCP4021T-503E/MC
MCP4131-103E/MF
MCP4131-104E/MF
MCP4131-502E/MF
MCP4131-503E/MF
MCP4131T-103E/MF
MCP4131T-104E/MF
MCP4131T-502E/MF
MCP4131T-503E/MF
MCP4132-103E/MF
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MCP4132-502E/MF
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MCP4132T-103E/MF
MCP4132T-104E/MF
MCP4132T-502E/MF
MCP4132T-503E/MF
MCP4141-103E/MF
MCP4141-104E/MF
MCP4141-502E/MF
MCP4141-503E/MF
MCP4141T-103E/MF
MCP4141T-104E/MF
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MCP4142-103E/MF
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MCP4142T-104E/MF
MCP4142T-502E/MF
MCP4142T-503E/MF
MCP4151-103E/MF
MCP4151-104E/MF
MCP4151-502E/MF

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
MCP4151-503E/MF
MCP4151T-103E/MF
MCP4151T-104E/MF
MCP4151T-502E/MF
MCP4151T-503E/MF
MCP4152-103E/MF
MCP4152-104E/MF
MCP4152-502E/MF
MCP4152-503E/MF
MCP4152T-103E/MF
MCP4152T-104E/MF
MCP4152T-502E/MF
MCP4152T-503E/MF
MCP4161-103E/MF
MCP4161-104E/MF
MCP4161-502E/MF
MCP4161-503E/MF
MCP4161T-103E/MF
MCP4161T-104E/MF
MCP4161T-502E/MF
MCP4161T-503E/MF
MCP4162-103E/MF
MCP4162-104E/MF
MCP4162-502E/MF
MCP4162-503E/MF
MCP4162T-103E/MF
MCP4162T-104E/MF
MCP4162T-502E/MF
MCP4162T-503E/MF
MCP4531T-103E/MF
MCP4531T-104E/MF
MCP4531T-502E/MF
MCP4531T-503E/MF
MCP4532T-103E/MF
MCP4532T-104E/MF
MCP4532T-502E/MF
MCP4532T-503E/MF
MCP4541T-103E/MF
MCP4541T-104E/MF
MCP4541T-502E/MF
MCP4541T-503E/MF
MCP4542-103PE/MF
MCP4542T-103E/MF

Affected Catalog Part Numbers (CPN)

PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
MCP4542T-103PE/MF
MCP4542T-104E/MF
MCP4542T-502E/MF
MCP4542T-503E/MF
MCP4551T-103E/MF
MCP4551T-104E/MF
MCP4551T-502E/MF
MCP4551T-503E/MF
MCP4552T-103E/MF
MCP4552T-104E/MF
MCP4552T-502E/MF
MCP4552T-503E/MF
MCP4561T-103E/MF
MCP4561T-104E/MF
MCP4561T-502E/MF
MCP4561T-503E/MF
MCP4561T-503E/MFOPP
MCP4562-103PE/MF
MCP4562T-103E/MF
MCP4562T-103PE/MF
MCP4562T-104E/MF
MCP4562T-104QE/MF
MCP4562T-502E/MF
MCP4562T-503E/MF
MCP4562T-503QE/MF
MCP4801-E/MC
MCP4801T-E/MC
MCP4811-E/MC
MCP4811T-E/MC
MCP4821-E/MC
MCP4821T-E/MC
MCP4901-E/MC
MCP4901T-E/MC
MCP4911-E/MC
MCP4911T-E/MC
MCP4921-E/MC
MCP4921T-E/MC
MCP6N16-001E/MF
MCP6N16-010E/MF
MCP6N16-100E/MF
MCP6N16T-001E/MF
MCP6N16T-010E/MF
MCP6N16T-100E/MF

Affected Catalog Part Numbers (CPN)

PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
MCP73831-2ACI/MC
MCP73831-2ATI/MC
MCP73831-2DCI/MC
MCP73831-3ACI/MC
MCP73831-4ADI/MC
MCP73831-5ACI/MC
MCP73831T-2ACI/MC
MCP73831T-2ATI/MC
MCP73831T-2DCI/MC
MCP73831T-3ACI/MC
MCP73831T-4ADI/MC
MCP73831T-5ACI/MC
MCP73832-2ACI/MC
MCP73832-2ATI/MC
MCP73832-2DCI/MC
MCP73832-3ACI/MC
MCP73832-4ADI/MC
MCP73832-5ACI/MC
MCP73832T-2ACI/MC
MCP73832T-2ATI/MC
MCP73832T-2DCI/MC
MCP73832T-3ACI/MC
MCP73832T-4ADI/MC
MCP73832T-5ACI/MC
MCP9804-E/MC
MCP9804-E/MCBBB
MCP9804T-E/MC
MCP9804T-E/MCBBB
MCP9805-BE/MC
MCP9805T-BE/MC
MCP9808T-E/MC
MCP98242-BE/MC
MCP98242-BE/MCBA2
MCP98242-CE/MC
MCP98242T-BE/MC
MCP98242T-BE/MCBA2
MCP98242T-BE/MCBA3
MCP98242T-BE/MCBAA
MCP98242T-BE/MCBAB
MCP98242T-BE/MCBAC
MCP98242T-CE/MC
MCP98243-BE/MC
MCP98243T-BE/MC

Affected Catalog Part Numbers (CPN)

PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
MCP98243T-BE/MCAA
MCP98243T-BE/MCAB
MCP9843-BE/MC
MCP9843T-BE/MC
PIC10F200-E/MC
PIC10F200-I/MC
PIC10F200T-E/MC
PIC10F200T-I/MC
PIC10F202-E/MC
PIC10F202-I/MC
PIC10F202T-E/MC
PIC10F202T-I/MC
PIC10F204-E/MC
PIC10F204-I/MC
PIC10F204T-E/MC
PIC10F204T-I/MC
PIC10F206-E/MC
PIC10F206-I/MC
PIC10F206T-E/MC
PIC10F206T-I/MC
PIC10F220-E/MC
PIC10F220-I/MC
PIC10F220T-E/MC
PIC10F220T-I/MC
PIC10F222-E/MC
PIC10F222-I/MC
PIC10F222T-E/MC
PIC10F222T-I/MC
PIC10F222T-I/MC051
PIC12F508-E/MC
PIC12F508-I/MC
PIC12F508-I/MC075
PIC12F508T-I/MC
PIC12F508T-I/MC075
PIC12F509-E/MC
PIC12F509-I/MC
PIC12F509T-I/MC
PIC12F510-E/MC
PIC12F510-I/MC
PIC12F510T-E/MC
PIC12F510T-I/MC
PIC12F519-E/MC
PIC12F519-I/MC

KSRA-20OSOQ751 -CCB 3041 and 3073 Initial Notice: Qualification of CuPdAu bond in selected products of the 160K wafer technology available in 8L DFN package at NSEB assembly site

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PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
PIC12F519T-E/MC
PIC12F519T-E/MC046
PIC12F519T-I/MC
PIC12F519T-I/MC034
PIC12F519T-I/MC045
PIC12F529-I/MC
PIC12F609-E/MD
PIC12F609-E/MF
PIC12F609-I/MD
PIC12F609-I/MF
PIC12F609T-E/MF
PIC12F609T-I/MD
PIC12F609T-I/MF
PIC12F615-E/MD
PIC12F615-E/MF
PIC12F615-H/MD
PIC12F615-I/MD
PIC12F615-I/MF
PIC12F615T-E/MF
PIC12F615T-I/MD
PIC12F615T-I/MD029
PIC12F615T-I/MF
PIC12F617-E/MF
PIC12F617-I/MF
PIC12F617T-E/MF
PIC12F617T-E/MF049
PIC12F617T-E/MF061
PIC12F617T-E/MF064
PIC12F617T-I/MF
PIC12F635-E/MF
PIC12F635-I/MD
PIC12F635-I/MF
PIC12F635T-I/MD
PIC12F635T-I/MD070
PIC12F635T-I/MF
PIC12F683-E/MD
PIC12F683-E/MF
PIC12F683-I/MD
PIC12F683-I/MF
PIC12F683T-E/MD
PIC12F683T-E/MF
PIC12F683T-I/MD
PIC12F683T-I/MF

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-20OSOQ751
CATALOG_PART_NBR
PIC12F752-E/MF
PIC12F752-I/MF
PIC12F752T-I/MF
PIC12HV609-E/MD
PIC12HV609-E/MF
PIC12HV609-I/MD
PIC12HV609-I/MF
PIC12HV609T-E/MF
PIC12HV609T-I/MD
PIC12HV609T-I/MF
PIC12HV615-E/MD
PIC12HV615-E/MF
PIC12HV615-I/MD
PIC12HV615-I/MF
PIC12HV615T-E/MF
PIC12HV615T-I/MD
PIC12HV615T-I/MF
PIC12HV615T-I/MF026
PIC12HV615T-I/MF027
PIC12HV615T-I/MF028
PIC12HV615T-I/MF030
PIC12HV752-E/MF
PIC12HV752-I/MF
PIC12HV752T-I/MF